

RECEIVED
CENTRAL FAX CENTER**FEB 09 2006****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE****Applicant(s):** Bian**Application No.:** 10/692,093**Filed:** 10/22/2003**Title:** METHOD OF SECOND STEP POLISHING IN
COPPER CMP WITH A POLISHING FLUID
CONTAINING NO OXIDIZING AGENT**Art Unit:**
1765**Examiner:**
Eric B. Chen*Eric B. Chen*
with [unclear]
*3/10/6***Attorney Docket No.:** 02005US**Commissioner for Patents**
P.O. Box 1450
Alexandria, VA 22313-1450**RESPONSE AFTER FINAL REJECTION****Dear Sir:**

In response to the Office Action of December 15, 2005, having a shortened statutory
deadline of March 15, 2005, please amend this application as follows: